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TC 1700



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE
FOR REFLOW SOLDERING

NOTICE OF APPEAL

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

The Applicants appeal to the Board of Patent Appeals and Interferences from the Official Action dated October 17, 2002 rejecting claims 1 - 24.

1. [X] The fee for filing this Notice of Appeal is attached.
[X] fee for other than small entity: \$320.00
2. [X] A check in the amount of \$320 is attached.
3. [X] The Commissioner is authorized to charge any deficiency in any patent application processing fees pursuant to

37 CFR §1.17, including extension of time fees pursuant to 37 CFR §1.17(a)-(d), associated with this communication and to credit any excess payment to Deposit Account No. 50-1079. A duplicate copy of this notice is attached.

Respectfully submitted,

Michael Tobias

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